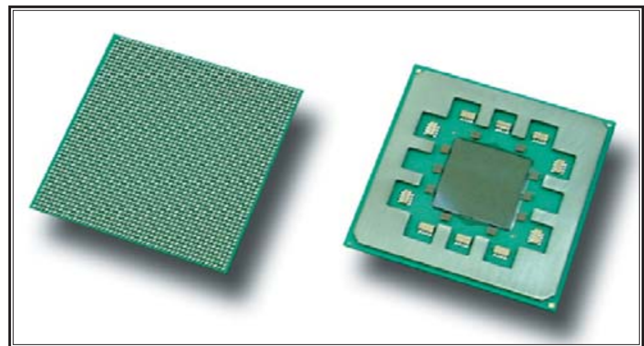
Packaging Substrate

Description

Fujitsu Interconnect Technologies Limited (FICT) provides design, manufacturing, maintenance, and consulting services for substrate packages.

As the functionality and performance of network systems, high-end servers, and mobile communication devices improves, the demand for high-performance, high pin count packages is increasing. This increasing demand requires new technologies, which incorporate high pin count and also delivers performance via impedance control, low crosstalk, DC/AC resistance, and low VG impedance. Sophisticated interconnect technology has become essential for meeting these needs by improving the density and reliability of the substrates for LSI package and module boards.

Fujitsu has been a technology leader in this area for a long time. FICT's GigaModule technology is available in a series of GigaModule product lines. FICT has incorporated several new technologies, materials and processes in these product lines to meet the market requirements at competitive pricing. These products are available in both flip chip and wire bond interconnection with variety of configurations. In addition we are developing next generation packages, which are expected to significantly improve performance and reduce costs.



Packaging Substrate (2500 pins)

Product Offerings

Packaging Substrate Manufacturing
- ASIC, FPGA, and graphics
- Build-up substrate from 1-2-1 to 6-2-6
- 20 μm Line and Space (15 μm is proto)
- Coreless structure (Proto)
- 2500 pins substrate is under production
- Low CTE, High Modulus, Low loss materials

Substrate Design Services

Simulation Services

Custom Project
- Layer reduction

Why FICT?

Technology leader
- Design
- Processes
- Materials
- Manufacturing

Proven quality at all plants

Global presence and support

Environmentally sensitive design and manufacturing

R&D commitment

Factory expansion and renovation

Long term and reliable partner

Packaging Substrate

Features

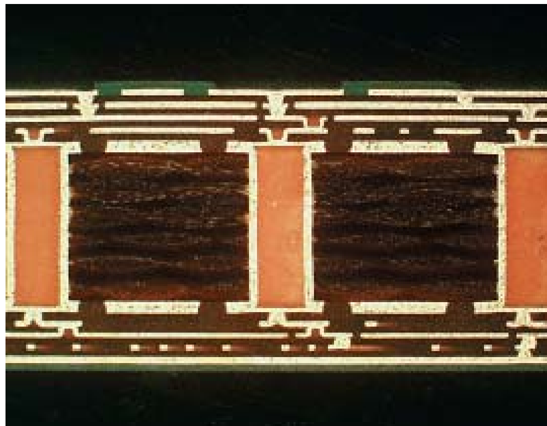
Coreless structure
Advanced materials
High density wiring by stacked via

Benefits

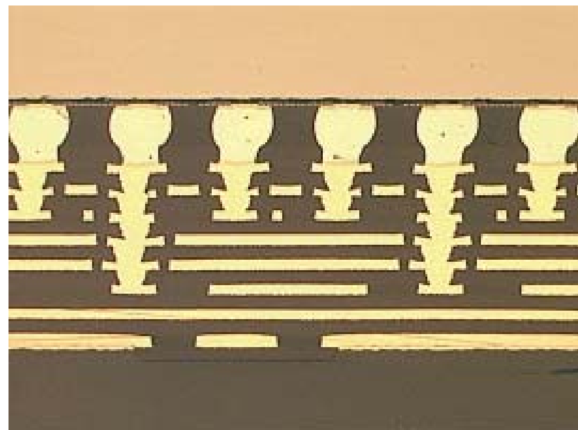
Cost reduction
Time reduction
Layer count reduction
High yield
Increased throughput
High-speed transmission
Size reduction

Technology

Stacked build-up technology
Coreless technology with low loop inductance
Impedance control
Crosstalk design in
Improved materials for both mechanical and electrical properties



GigaModule-2 (4-2-4)



GigaModule-4 (8L)
Coreless

FICT Factories approved by over 35 Customers

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